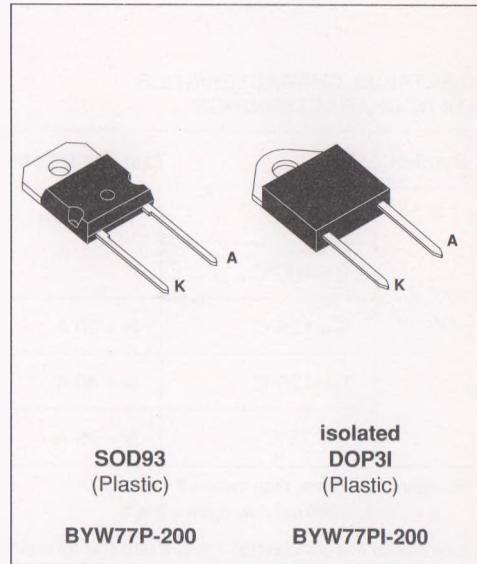


HIGH EFFICIENCY FAST RECOVERY RECTIFIER DIODES

FEATURES

- SUITED FOR SMPS
- VERY LOW FORWARD LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- HIGH SURGE CURRENT CAPABILITY
- HIGH AVALANCHE ENERGY CAPABILITY
- INSULATED VERSION :
 - Insulating voltage = 2500 V DC
 - Capacitance = 12 pF



DESCRIPTION

Single chip rectifier suited for switchmode power supply and high frequency DC to DC converters. Packaged in SOD93, or DOP3I this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter			Value	Unit
$I_F(RMS)$	RMS forward current			50	A
$I_F(AV)$	Average forward current $\delta = 0.5$	SOD93	$T_c=125^\circ C$	25	A
		TOP3I	$T_c=100^\circ C$	25	
I_{FSM}	Surge non repetitive forward current		$t_p=10ms$ sinusoidal	500	A
T_{Stg} T_j	Storage and junction temperature range			- 40 to + 150 - 40 to + 150	°C °C

Symbol	Parameter	BYW77P-/PI-				Unit
		50	100	150	200	
V_{RRM}	Repetitive peak reverse voltage	50	100	150	200	V

THERMAL RESISTANCE

Symbol	Parameter		Value	Unit
$R_{th} (j-c)$	Junction to case	SOD93	1.0	°C/W
		DOP3I	1.8	

ELECTRICAL CHARACTERISTICS
STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
I_R *	$T_j = 25^\circ C$	$V_R = V_{RRM}$			25	μA
	$T_j = 100^\circ C$				2.5	mA
V_F **	$T_j = 125^\circ C$	$I_F = 20 A$			0.85	V
	$T_j = 125^\circ C$	$I_F = 40 A$			1.00	
	$T_j = 25^\circ C$	$I_F = 40 A$			1.15	

Pulse test : * $t_p = 5 \text{ ms}$, duty cycle < 2 %** $t_p = 380 \mu\text{s}$, duty cycle < 2 %

To evaluate the conduction losses use the following equation :

$$P = 0.7 \times I_F(AV) + 0.0075 \times I_F^2(\text{RMS})$$

RECOVERY CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
trr	$T_j = 25^\circ C$	$I_F = 0.5A$	$I_{rr} = 0.25A$			35
		$I_F = 1A$	$V_R = 30V$			50
tfr	$T_j = 25^\circ C$	$I_F = 1A$	$dI_F/dt = -50A/\mu s$		10	ns
V_{FP}	$T_j = 25^\circ C$	$I_F = 1A$	$V_{FR} = 1.1 \times V_F$		1.5	V

Fig.1 : Average forward power dissipation versus average forward current.

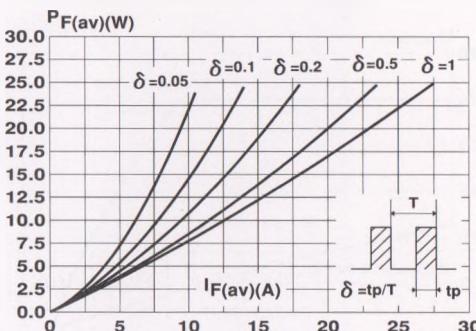


Fig.3 : Forward voltage drop versus forward current (maximum values).

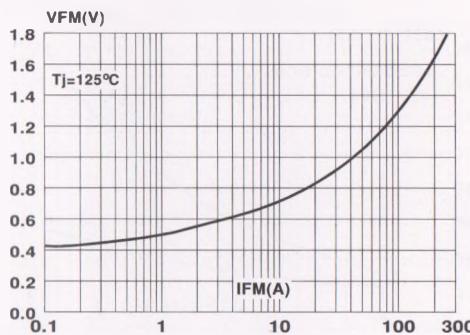


Fig.5 : Non repetitive surge peak forward current versus overload duration.
(BYW81P)

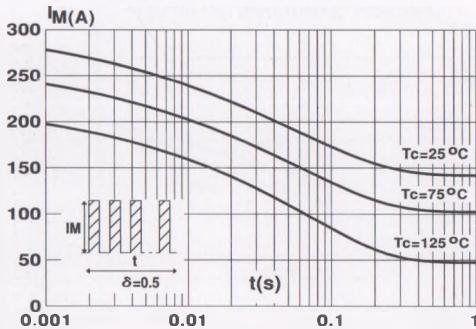


Fig.2 : Peak current versus form factor.

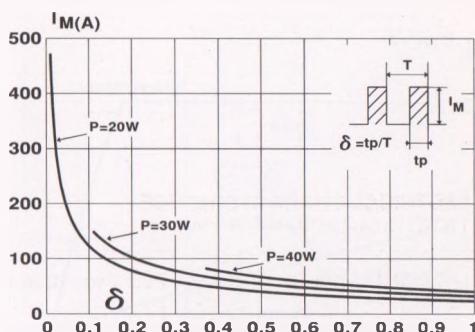


Fig.4 : Relative variation of thermal impedance junction to case versus pulse duration.

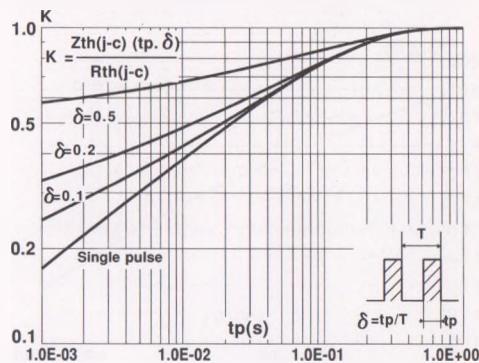


Fig.6 : Non repetitive surge peak forward current versus overload duration.
(BYW81PI)

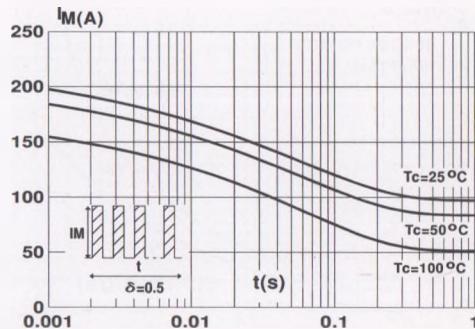


Fig.7 : Average current versus ambient temperature.
(duty cycle : 0.5) (SOD93)

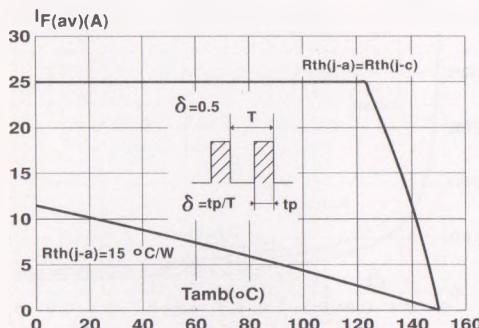


Fig.9 : Junction capacitance versus reverse voltage applied (Typical values).

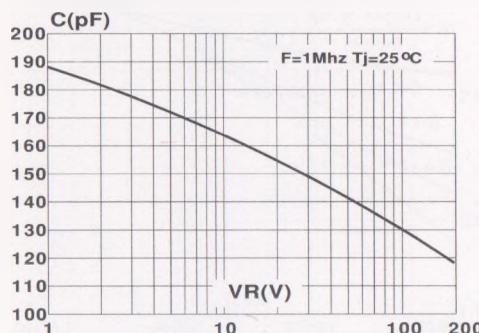


Fig.11 : Peak reverse current versus dIF/dt.

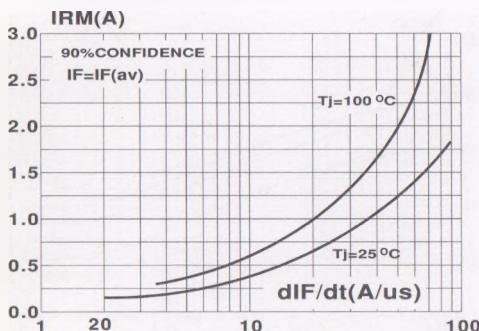


Fig.8 : Average current versus ambient temperature.
(duty cycle : 0.5) (DOP3I)

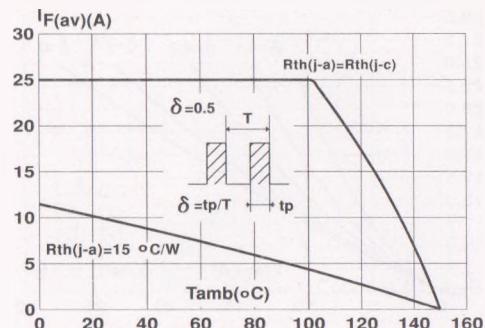


Fig.10 : Recovery charges versus dIF/dt.

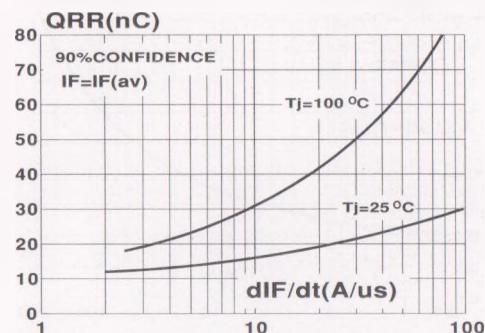


Fig.12 : Dynamic parameters versus junction temperature.

